

# SOT813-2

plastic thermal enhanced very thin quad flat package; no leads; 72 terminals

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	Q (quad)
<b>Package type descriptive code</b>	HVQFN72
<b>Package type industry code</b>	HVQFN72
<b>Package style descriptive code</b>	HVQFN (thermal enhanced very thin quad flatpack; no leads)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>IEC package outline code</b>	---
<b>JEDEC package outline code</b>	MO-220
<b>JEITA package outline code</b>	---
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	13-10-2004

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	9.9	-	10	10.1	mm
E	package width	9.9	-	10	10.1	mm
A	seated height	[tbd]	-	[tbd]	1	mm
e	nominal pitch	-	-	0.5	-	mm
n <sub>2</sub>	actual quantity of termination	-	-	72	-	

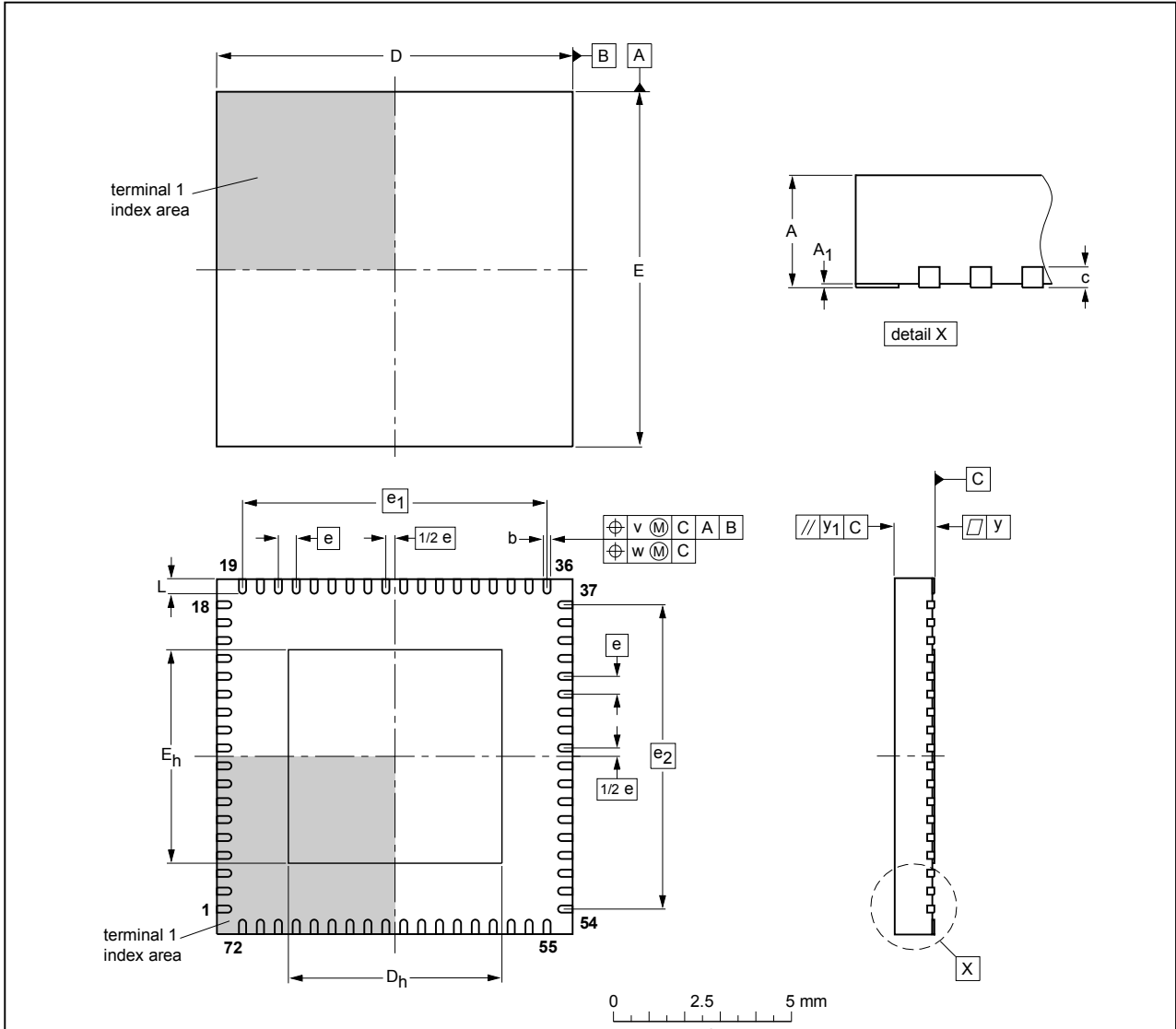


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## 2. Package outline

HVQFN72: plastic thermal enhanced very thin quad flat package; no leads; 72 terminals; body 10 x 10 x 0.85 mm

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DIMENSIONS (mm are the original dimensions)

UNIT	A <sup>(1)</sup> max.	A <sub>1</sub>	b	c	D <sup>(1)</sup>	D <sub>h</sub>	E <sup>(1)</sup>	E <sub>h</sub>	e	e <sub>1</sub>	e <sub>2</sub>	L	v	w	y	y <sub>1</sub>
mm	1	0.05 0.00	0.30 0.18	0.2	10.1 9.9	6.15 5.85	10.1 9.9	6.15 5.85	0.5	8.5	8.5	0.5 0.3	0.1	0.05	0.05	0.1

**Note**

1. Plastic or metal protrusions of 0.075 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT813-2	---	MO-220	---			04-10-04 04-10-13

Fig. 1. Package outline HVQFN72 (SOT813-2)

3. Soldering

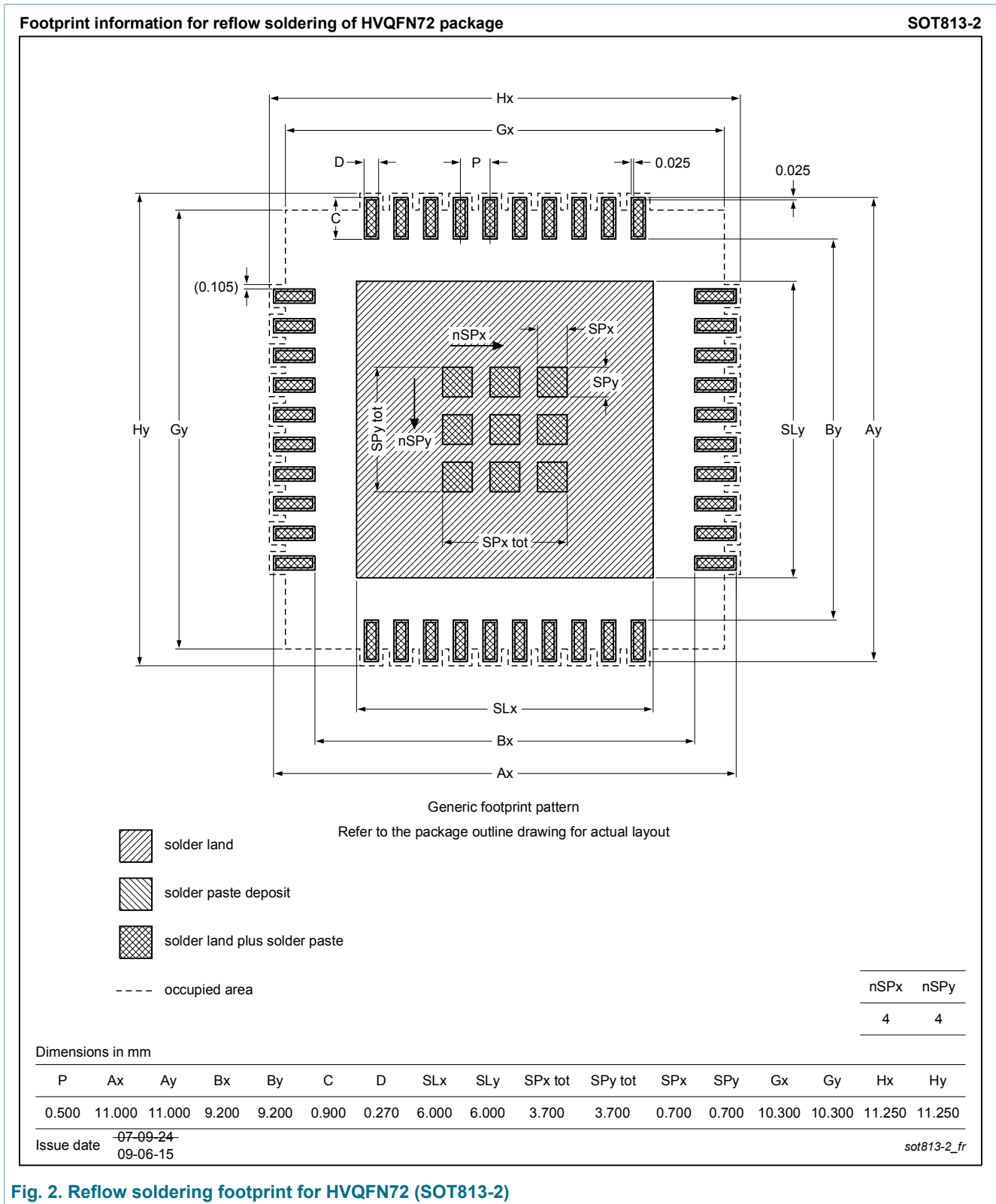


Fig. 2. Reflow soldering footprint for HVQFN72 (SOT813-2)

## 4. Legal information

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